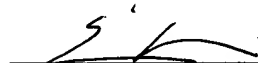


**REMARKS**

The specification has been amended to correct typographical errors. Examination on the merits is requested.

Respectfully submitted,



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VERSION WITH MARKINGS TO SHOW CHANGES MADE

IN THE SPECIFICATION

Page 19, Line 11

FIG. 2B is a view illustrating a structure of a second cross-linking molecule used in Example [2] 1 of the method for forming an interlayer dielectric film of the first embodiment.

Page 20 continuing on page 21 , line 24

FIGS. [13A] ~~12A~~ through [13C] ~~12C~~ are views illustrating steps of a method for forming an interconnection of the third embodiment.

Page 21, line 2

FIGS. [14A] ~~13A~~ and [14B] ~~13B~~ are views illustrating steps of the method for forming an interconnection of the third embodiment.

Page 31, line 18

In the Example [2], the imide formation reaction between an amino group and a carboxylic group and a carboxylic group was employed as the polymerization reaction between the first and the second cross-linking molecules. The reaction is not limited to the above, but reaction systems such as amide bond reaction, ether bond reaction, C-C bond reaction, and C-N bond reaction may be employed.